

Abstract of the Disclosure:

In a semiconductor device, rewirings 3 for connecting a semiconductor chip 1a, a semiconductor chip 1b and external connecting terminals 4 with each other are formed on the semiconductor chip 1a. An insulating resin 6 having opening portions in regions for forming the external connecting terminals 4 at peripheral portion of the semiconductor chip 1a and another opening portions in another region for mounting the semiconductor chip 1b at the central of the semiconductor chip 1a is overlaid on the rewirings 3. The external connecting terminals 4 consisting of BGA are formed in the opening portions of the regions for forming the external connecting terminals 4 through lands 5. The semiconductor chip 1b is connected to another opening portions of another region for mounting the semiconductor chip 1b by flip-chip structure through electrodes 11 and bumps 8. A junction surface of the bumps 8 is sealed by a sealing resin 7. The semiconductor chip 1b is mounted on the same surface as that the external connecting terminals 4 are formed. The under surface of the semiconductor chip 1b is ground in order that the semiconductor chip 1b may be shorter than the external connecting terminals 4. The semiconductor chip 1b is thereby mounted with high density.